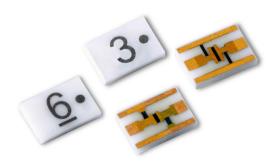
### TSX Series

### Fixed Chip Attenuators



Smiths Interconnect is a leading provider of chip attenuators offering the widest selection of products from DC to Q-band, backed by proven performance and significant heritage. Chip components are offered on Alumina, Aluminum Nitride, Beryllium Oxide, and CVD Diamond for a wide range of applications.

The TSX Series of chip attenuators pushes the boundaries of Size, Weight and Power in a cost effective, easy to implement surface mount solution, suitable for a wide array of applications.

The TSX Series offers excellent broadband RF performance to 50 GHz while delivering increased power handling in a small surface mount format factor.

The chip attenuator design offers 1 to 3 watts of power handling performance and multiple attenuation values are available for surface mounting. The use of a robust, proven all thin film process technology on an alumina substrate provides a product suitable for harsh environments, such as those of Space and Defense applications.



TSX Chip
Attenuators offers
excellent performance
and power from
DC-50 GHz in a small
0604 package size.

### Features and Benefits

- Small form factor Reduces overall footprint
- Surface mountable Ideal for pick and place applications
- Broad frequency range Reduces BOM count
- Low VSWR Increases transmitted power
- Wide range of attenuation values 1-10, 15 and 20dB
- Tight attenuation tolerance For optimal performance

### **Applications**

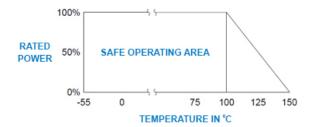
- Amplifier Circuits
- Transmit/Receive Modules
- Up/Down Converters
- Instrumentation
- Satellite Communications
- Radar
- 5G

# **Technical Characteristics**

Mounting Configuration Options	Planar										
Electrical	•										
Nominal Impedance	50 ohms										
Frequency Range	DC -50 GHz										
Attenuation Values	0-10, 15 & 20 dB in 1 dB Increments										
Attenuation Accuracy		ATTENUATION ACCURACY (dB)									
	Atte Valu	nuation ve (dB)	DC-4	40-5	40-50 GHz						
		0	Continuity Only								
	1-10 15 & 20		±	0.50	± 0.5						
			±	0.50	± 3.0						
Input Power CW			INPUT POWER (CW)								
	dB	Watts	dB	Watts	dB	Watts					
	0-1	3.0	2-3	2.0	4-20	1.0					
Peak Power	10X CW power	based on 1 µS pulse	width @ 1% Duty	Cycle							
VSWR	VSWR										
		dB		10 GHz	40-50 GHz						
		0		Continu	uity Only						
	1-10 15-20		1.20	:1 Max	1.25:1 Max						
			1.20	:1 Max	1.25:1 Max						
Environmental											
Operating Temperature	-55°C to +150°C										
Storage Temperature	-65°C to +150°C										
Temperature Coefficient	±200 PPM/°C Max										
Moisture Sensitivity Level	MSL 1 - Unlimited										
Mechanical											
Substrate Material	Alumina (Al <sub>2</sub> O <sub>3</sub> ) 96%										
Resistive Film	Thin Film, Tantalum Nitride										
Terminal Material	Thin Film, Solderable Gold over Nickel										
Protective Coating	Silicon Nitride										
Marking											
Unit Marking	Orientation dot and dB Value										
Quality Assurance											
	Sample visual a	nd mechanical inspe	ction - 1.0 AQL p	er mechanical drawi	ng requirements.						
	Periodic electrical inspection performed for commerical grade products.										
	High reliability tested products are available per MIL-PRF-55342.										
Packaging											
Standard Packaging	Tape and Reel o	or Waffle Pack									

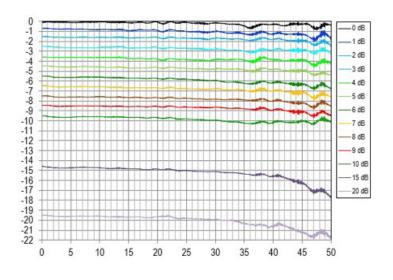
2

## Power Derating Curve

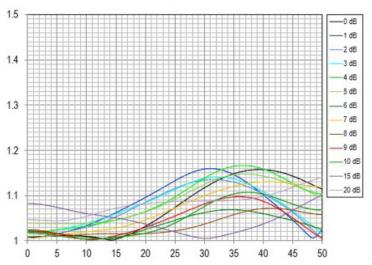


## Typical Data

#### TSX Series Attenuation

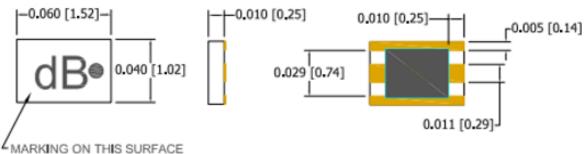


#### TSX Series VSWR



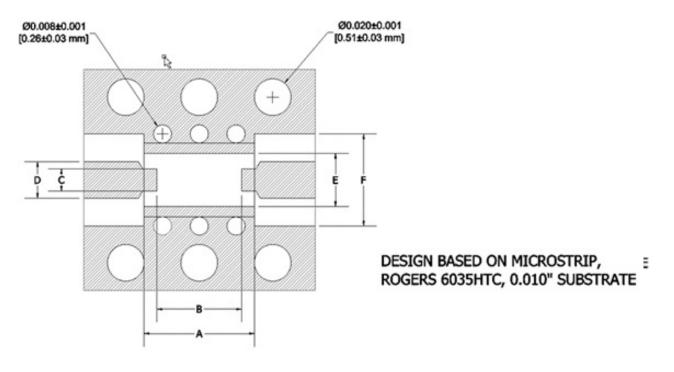
### Mechanical

#### **TSX Series**



## Suggested Mounting Footprint

		Inches				Millimeters						
Part Number	Α	В	С	D	Е	F	А	В	С	D	Е	F
TSXdB.00	0.060	0.046	0.012	0.020	0.029	0.050	1.52	1.17	0.30	0.51	0.74	1.27



## How To Order

Specify Model Number: TSXdB.00

T S X	2	3
1 Series Name	T S X Series	
2 Attenuation Value	0 0 00 dB through 10 dB 1 5 15 dB	2 0 20 dB
3 SINT Code	. 0 0	